Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: <u>ti.com/support</u>

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: **06/12/2022**

Details for "TPS7A1650DRBT"

Current Product Information

	TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
ĺ	TPS7A1650DRBT	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DRB 8	3x3x0.9	20.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm	
Bond Wire								
Precious Metals	Gold	7440-57-5	0.053058	100	1000000	0.255109	2551	
Sub-Total			0.053058	100	1000000	0.255109	2551	
Die Attach Adhesive								
Precious Metals	Silver	7440-22-4	0.335487	79.999952	800000	1.61306	16131	
Thermoplastics	Ероху	85954-11-6	0.083872	20.000048	200000	0.403266	4033	
Sub-Total			0.419359	100	1000000	2.016327	20163	
Lead Frame								
Copper and Its Alloys	Copper	7440-50-8	7.503211	97.444299	974443	36.076309	360763	
Copper and Its Alloys	Iron	7439-89-6	0.180865	2.348896	23489	0.86962	8696	
Copper and Its Alloys	Phosphorus	7723-14-0	0.006322	0.082104	821	0.030397	304	
Zinc and Its Alloys	Zinc	7440-66-6	0.009602	0.124701	1247	0.046168	462	
Sub-Total			7.7	100	1000000	37.022493	370225	
Lead Frame Plating	·	•						
Nickel and Its Alloys	Nickel	7440-02-0	0.09512	95.12	951200	0.457348	4573	
Precious Metals	Gold	7440-57-5	0.00078	0.78	7800	0.00375	38	
Precious Metals	Palladium	7440-05-3	0.0041	4.1	41000	0.019713	197	
Sub-Total			0.1	100	1000000	0.480812	4808	
Mold Compound								
Other Inorganic Materials	Fused Silica	60676-86-0	9.885166	90.500003	905000	47.529025	475290	
Other Plastics and Rubber	Carbon Black	1333-86-4	0.054614	0.499998	5000	0.26259	2626	
Thermoplastics	Ероху	85954-11-6	0.983055	8.999999	90000	4.726642	47266	
Sub-Total			10.922835	100	1000000	52.518258	525183	
Semiconductor Device								
Ceramics / Glass	Doped Silicon	7440-21-3	1.602915	100	1000000	7.707001	77070	
Sub-Total			1.602915	100	1000000	7.707001	77070	
Total			20.798167			100	1000000	

Important Not

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.